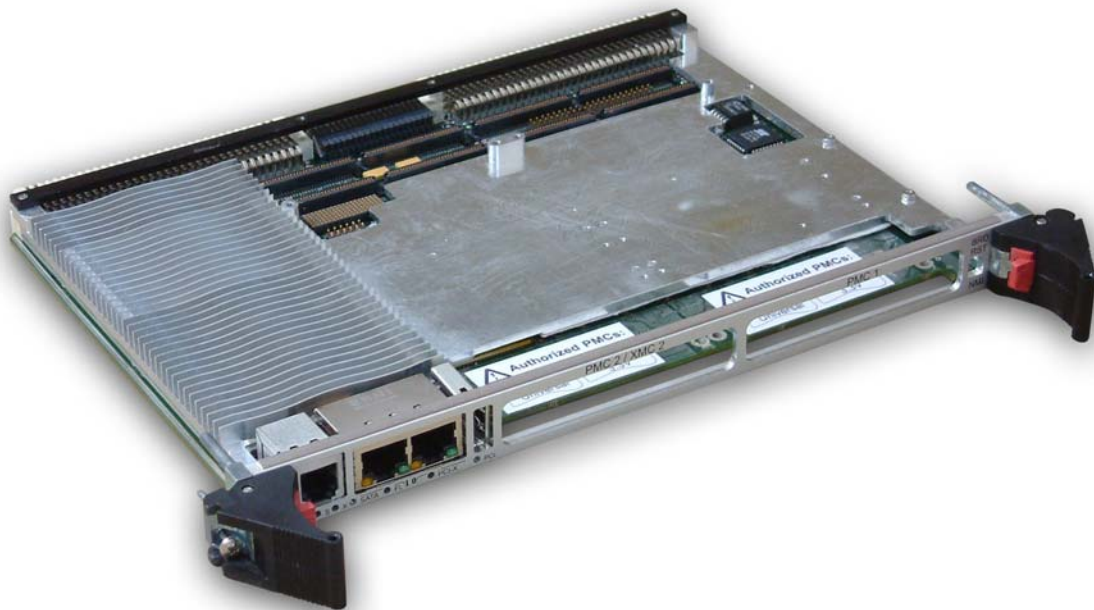


» PENTXM2/RA & PENTXM4/RA «



User's Guide Supplement

CA.DT.A72-2e - October 2010

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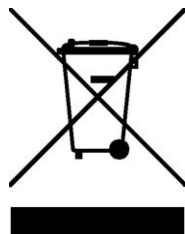
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Environmental protection is a high priority with Kontron.

Kontron follows the DEEE/WEEE directive.

You are encouraged to return our products for proper disposal.

The Waste Electrical and Electronic Equipment (WEEE) Directive aims to:

- > reduce waste arising from electrical and electronic equipment (EEE)
- > make producers of EEE responsible for the environmental impact of their products, especially when they become waste
- > encourage separate collection and subsequent treatment, reuse, recovery, recycling and sound environmental disposal of EEE
- > improve the environmental performance of all those involved during the lifecycle of EEE

Conventions

This guide uses several types of notice: Note, Caution, ESD.



Note: this notice calls attention to important features or instructions.



Caution: this notice alert you to system damage, loss of data, or risk of personal injury.



ESD: This banner indicates an Electrostatic Sensitive Device.

All numbers are expressed in decimal, except addresses and memory or register data, which are expressed in hexadecimal. The prefix `0x` shows a hexadecimal number, following the `C` programming language convention.

The multipliers `k`, `M` and `G` have their conventional scientific and engineering meanings of $*10^3$, $*10^6$ and $*10^9$ respectively. The only exception to this is in the description of the size of memory areas, when `K`, `M` and `G` mean $*2^{10}$, $*2^{20}$ and $*2^{30}$ respectively.



When describing transfer rates, `k` `M` and `G` mean $*10^3$, $*10^6$ and $*10^9$ *not* $*2^{10}$ $*2^{20}$ and $*2^{30}$.

In PowerPC terminology, multiple bit fields are numbered from 0 to n, where 0 is the MSB and n is the LSB. PCI and CompactPCI terminology follows the more familiar convention that bit 0 is the LSB and n is the MSB.

Signal names ending with an asterisk (*) or a hash (#) denote active low signals; all other signals are active high.

Signal names follow the PICMG 2.0 R3.0 CompactPCI Specification and the PCI Local Bus 2.3 Specification.

For Your Safety

Your new Kontron product was developed and tested carefully to provide all features necessary to ensure its compliance with electrical safety requirements. It was also designed for a long fault-free life. However, the life expectancy of your product can be drastically reduced by improper treatment during unpacking and installation. Therefore, in the interest of your own safety and of the correct operation of your new Kontron product, you are requested to conform with the following guidelines.

High Voltage Safety Instructions



Warning!

All operations on this device must be carried out by sufficiently skilled personnel only.



Caution, Electric Shock!

Before installing a not hot-swappable Kontron product into a system always ensure that your mains power is switched off. This applies also to the installation of piggybacks. Serious electrical shock hazards can exist during all installation, repair and maintenance operations with this product. Therefore, always unplug the power cable and any other cables which provide external voltages before performing work.

Special Handling and Unpacking Instructions



ESD Sensitive Device!

Electronic boards and their components are sensitive to static electricity. Therefore, care must be taken during all handling operations and inspections of this product, in order to ensure product integrity at all times

Do not handle this product out of its protective enclosure while it is not used for operational purposes unless it is otherwise protected.

Whenever possible, unpack or pack this product only at EOS/ESD safe work stations. Where a safe work station is not guaranteed, it is important for the user to be electrically discharged before touching the product with his/her hands or tools. This is most easily done by touching a metal part of your system housing.

It is particularly important to observe standard anti-static precautions when changing piggybacks, ROM devices, jumper settings etc. If the product contains batteries for RTC or memory backup, ensure that the board is not placed on conductive surfaces, including anti-static plastics or sponges. They can cause short circuits and damage the batteries or conductive circuits on the board.

General Instructions on Usage

In order to maintain Kontron's product warranty, this product must not be altered or modified in any way. Changes or modifications to the device, which are not explicitly approved by Kontron and described in this manual or received from Kontron's Technical Support as a special handling instruction, will void your warranty.

This device should only be installed in or connected to systems that fulfill all necessary technical and specific environmental requirements. This applies also to the operational temperature range of the specific board version, which must not be exceeded. If batteries are present, their temperature restrictions must be taken into account.

In performing all necessary installation and application operations, please follow only the instructions supplied by the present manual.

Keep all the original packaging material for future storage or warranty shipments. If it is necessary to store or ship the board, please re-pack it as nearly as possible in the manner in which it was delivered.

Special care is necessary when handling or unpacking the product. Please consult the special handling and unpacking instruction on the previous page of this manual.

Table Of Contents

Chapter 1 - Introduction	1
1.1 Objectives	2
1.2 Related Documents	2
Chapter 2 - Characteristics of the Board	3
2.1 PENTXM2/RA & PENTXM4/RA Specificities	3
2.2 Batteryless Operation and Non-Volatile Board Settings	4
2.3 Board Identification	5
2.4 Environmental Specifications	6
2.5 Hardware Configuration	7
2.5.1 NAND Flash Protection	8
2.6 Mechanical Specifications	10
2.7 MTBF Data	11
2.8 Thermal Performance	12

List Of Figures

Figure 1: PENTXM2/RA & PENTXM4/RA - Overview	1
Figure 2: PENTXM2/RA & PENTXM4/RA Identification	5
Figure 3: PENTXM2/RA & PENTXM4/RA Jumpers Locations and Default Settings	7
Figure 4: InsydeH2O: IDE Configuration	8
Figure 5: VME Dimensions	10
Figure 6: Thermal Performance - PENTXM2/RA @ 1.67 GHz	12
Figure 7: Thermal Performance - PENTXM2/RA @ 1.33 GHz	13
Figure 8: Air Flow Direction	13
Figure 9: Thermal Performance – PENTXM4/RA @ 1.67 GHz	14
Figure 10: Thermal Performance (Estimation)– PENTXM4/RA @ 1.33 GHz	14

List Of Tables

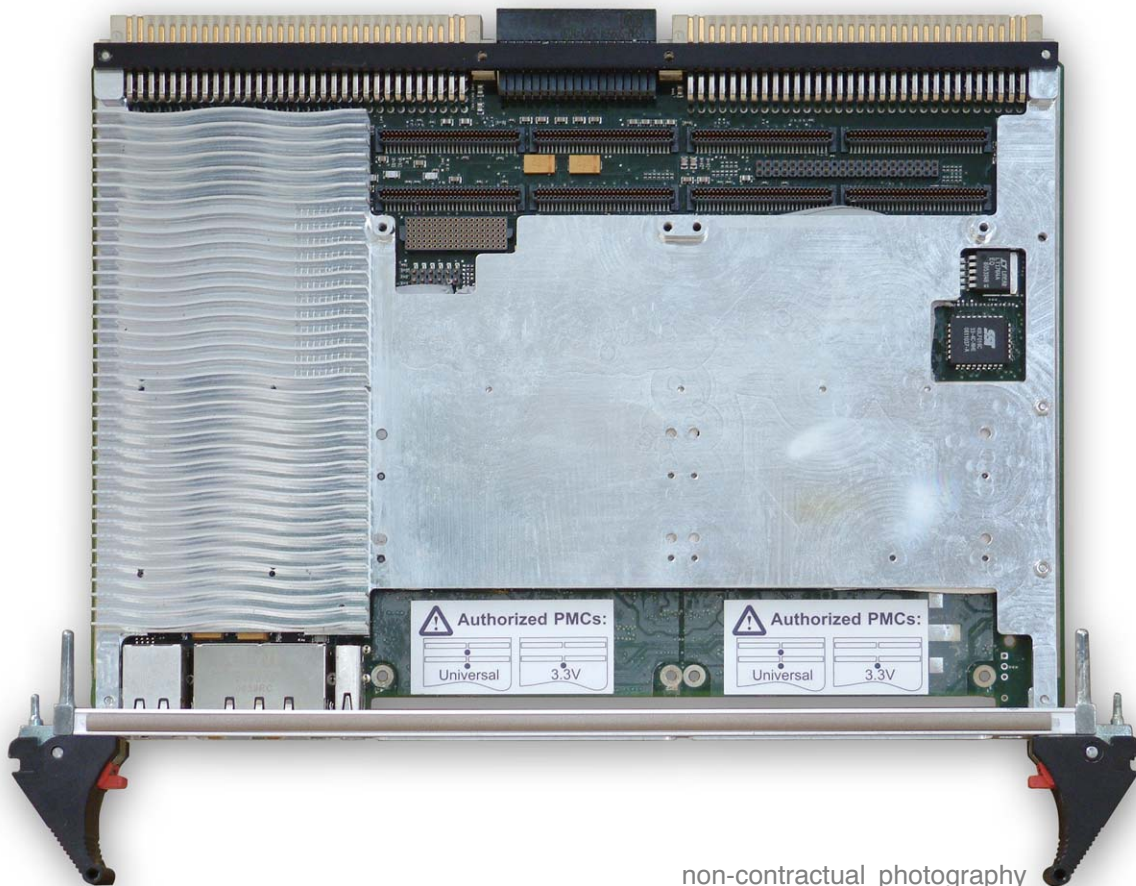
Table 1: PENTXM2/RA & PENTXM4/RA Specificities	3
Table 2: Environmental Specifications	6
Table 3: Jumper Description: NAND Flash Protection	8
Table 4: Control of the NAND Flash Protection	9
Table 5: MTBF Data	11

Chapter 1 - Introduction



Functional changes that differ from previous version of the document are identified by a vertical bar in the margin.

The PENTXM2/RA & PENTXM4/RA boards use "The Ruggedizer", a Kontron proven technology to meet the requirements for harsh environments. With an operational temperature range from -40°C up to $+71^{\circ}\text{C}$ (VITA 47 AC3) and its mechanical environmental performances, the PENTXM2/RA & PENTXM4/RA are designed for severe environmental applications with high levels of shock and vibration, small space envelope and restricted cooling such as required in military, marine, avionics, sheltered and industrial applications.



non-contractual photography

Figure 1: PENTXM2/RA & PENTXM4/RA - Overview

» Order Code

PENTXM2-RA34S-10000	Rugged Air-Cooled RA Class Dual-Core Intel Xeon @1.67 GHz 1 GB DDR2-SDRAM 4 GB soldered Flash Disk Coated
PENTXM2-RA36S-10000	Rugged Air-Cooled RA Class Dual-Core Intel Xeon @1.67 GHz 2 GB DDR2-SDRAM 4 GB soldered Flash Disk Coated
PENTXM2-RA38S-10000	Rugged Air-Cooled RA Class Dual-Core Intel Xeon @1.67 GHz 4 GB DDR2-SDRAM 4 GB soldered Flash Disk Coated

1.1 Objectives

This document describes the specificities of the PENTXM2/RA & PENTXM4/RA boards compared to the PENTXM2/SA and PENTXM4/SA boards. It focuses on the features which are specific to the air-cooled version of the boards.

This document does not supersede the "PENTXM2 and PENTXM4 Boards - User's Guide" which contains important information for unpacking, identifying, configuring, installing and operating the PENTXM2 and PENTXM4 boards and which should be read first.



- The "User's Guide" and "Connection Guide" manuals (see section 1.2 "Related Documents") reflect the most recent version of the Kontron products.
- The "Hardware Release Notes" documentation (see section 1.2 "Related Documents") helps to keep track of various evolutions of the products.

1.2 Related Documents

» Hardware Documentation

- > PENTXM2 and PENTXM4 Hardware Release Notes CA.DT.A09
- > PENTXM2 and PENTXM4 User's Guide CA.DT.A07
- > PENTXM2 and PENTXM4 Connection Guide CA.DT.A10
- > PENTXM2/RC and PENTXM4/RC Supplement User's Guide CA.DT.A08
- > PENTXM2/RA & PENTXM4/RA Supplement User's Guide (this manual) CA.DT.A72

» Firmware Documentation

- > InsydeH20 Firmware for PENTXM2 and PENTXM4 - User Reference Manual SD.DT.E86
- > PENTXM2 and PENTXM4 XBIT User's Guide SD.DT.E90
- > PENTXM2 and PENTXM4 IPMI BMC User's Manual SD.DT.F12

» Software Documentation

- > Release Notes RHEL5.2 on PENTXM2 and PENTXM4 Boards SD.DT.F34
- > Release Notes RHEL5 on PENTXM2 and PENTXM4 Boards SD.DT.F28
- > Release Notes RHEL4 on PENTXM2 and PENTXM4 Boards SD.DT.E82
- > Release Notes Windows XP on PENTXM2 and PENTXM4 Boards SD.DT.F39

Chapter 2 - Characteristics of the Board

2.1 PENTXM2/RA & PENTXM4/RA Specificities

The PENTXM2/RA & PENTXM4/RA boards have the same features as the PENTXM2/SA & PENTXM4/SA boards (refer to the “PENTXM2 and PENTXM4” Boards - User’s Guide” for more information) except for the following items which are fully described in associated section below:

FUNCTION	DESCRIPTION	SEE ALSO
Battery	No battery available onboard	Section 2.2 page 5
Board Identification	Specific ruggedizer identification	Section 2.3 page 6
Environmental Specifications	Depend on environmental class	Section 2.4 page 7
Hardware Configuration	Depend on the environmental class	Section 2.5 page 8
Mechanical Specifications	Depend on the environmental class	Section 2.6 page 11
MTBF	Depend on the environmental class	Section 2.7 page 12
System Flash	System Flash soldered onboard	
Thermal Performance	Depend on the environmental class	Section 2.8 page 13

Table 1: PENTXM2/RA & PENTXM4/RA Specificities

2.2 Batteryless Operation and Non-Volatile Board Settings

For specific applications, the limited lifetime of the battery in extreme environmental conditions is an issue. In this case, system requirement forbids the use of a battery.

The PENTXM2/RA & PENTXM4/RA boards operate safely without a battery fitted. In this case, the non-volatile board settings are managed this way:

- ▶ All BIOS user settings are kept forever (in a specific area of the BIOS Flash)
- ▶ By default, all PENTXM2/RA & PENTXM4/RA boards are delivered without a battery fitted, so the Date/Time is lost at each power-on/power-off and the BIOS displays: **01/01/2001 00:00/00**

2.3 Board Identification

The PENTXM2/RA & PENTXM4/RA boards are identified by labels fitted to the bottom side. These labels are at the same location and have the same meaning (except the "Board Identification" label) as the PENTXM2/SA boards labels (refer to the "PENTXM2 and PENTXM4" Boards - User's Guide" for more information).

- ▶ The "Board Identification" label prefix of a PENTXM2/RA & PENTXM4/RA board is PENTXM2-RA or PENTXM4-RA.
- ▶ In addition, the ruggedizer is identified by:
 - ▶ the "Ruggedizer Identification" (printed on the ruggedizer). AA
 - ▶ the "Engineering Change Level" (E.C. Level) of the ruggedizer. AB

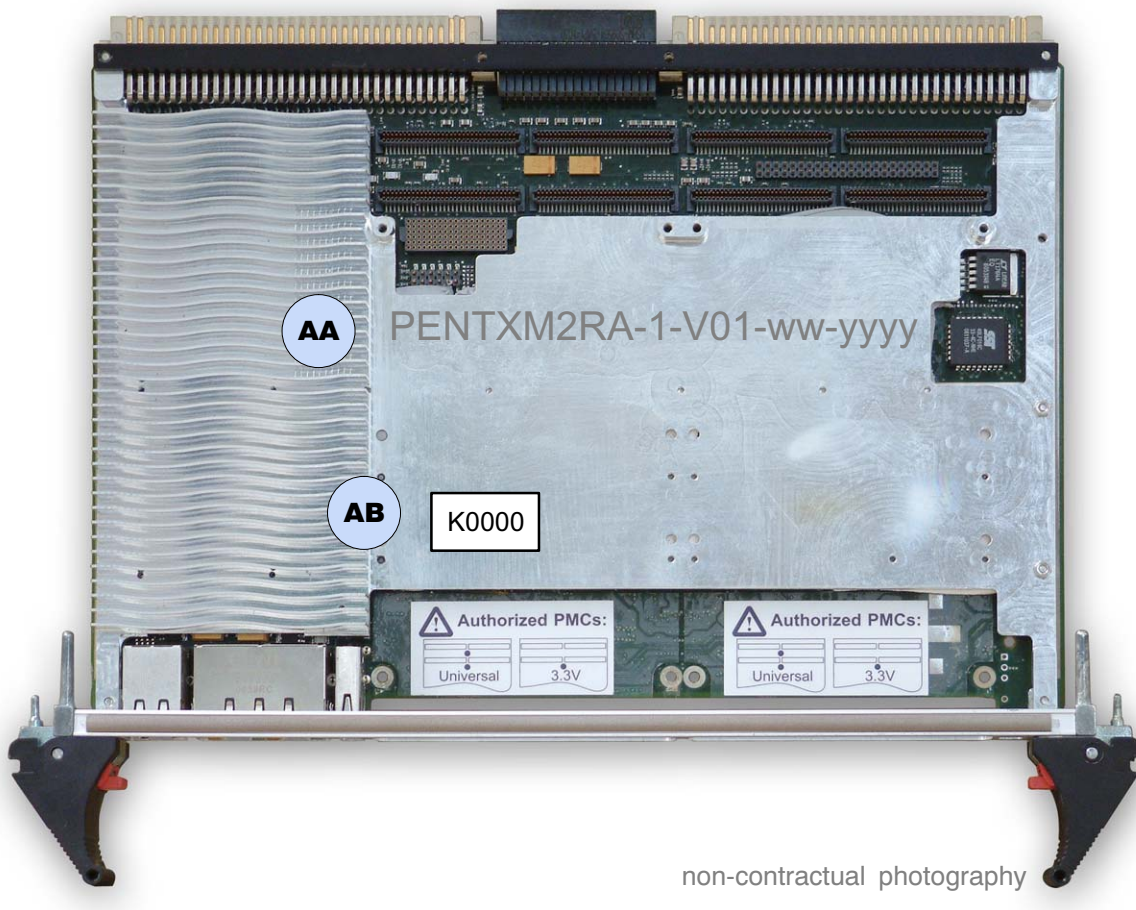


Figure 2: PENTXM2/RA & PENTXM4/RA Identification

2.4 Environmental Specifications

Environmental Specifications	RA (Rugged Air-Cooled)
Conformal Coating	Standard
Temperature	
Cooling Method	Air-Cooled
Operating	-40° to +71° C - VITA 47 - Class AC3
Storage	-45° to +100° C
Vibration Sine (Operating)	20 / 2000 Hz 3g
Random Vibration	VITA 47 - Class V2
Shock (Operating)	Half Sine 40 g / 20 ms
Altitude (Operating)	-1,640 to 33,000 ft
Relative Humidity	95% without condensation

Table 2: Environmental Specifications



Please, check in chapter 2.8 the graph of operating temperature usage versus air-flow.

2.5 Hardware Configuration



When setting jumpers, avoid touching areas of integrated circuitry; static discharge can damage circuits.

To ensure proper operation of the PENTXM2/RA & PENTXM4/RA board, you may need to check its jumpers configuration. Figure 3 illustrates the placement of the jumpers on the board and their default settings.

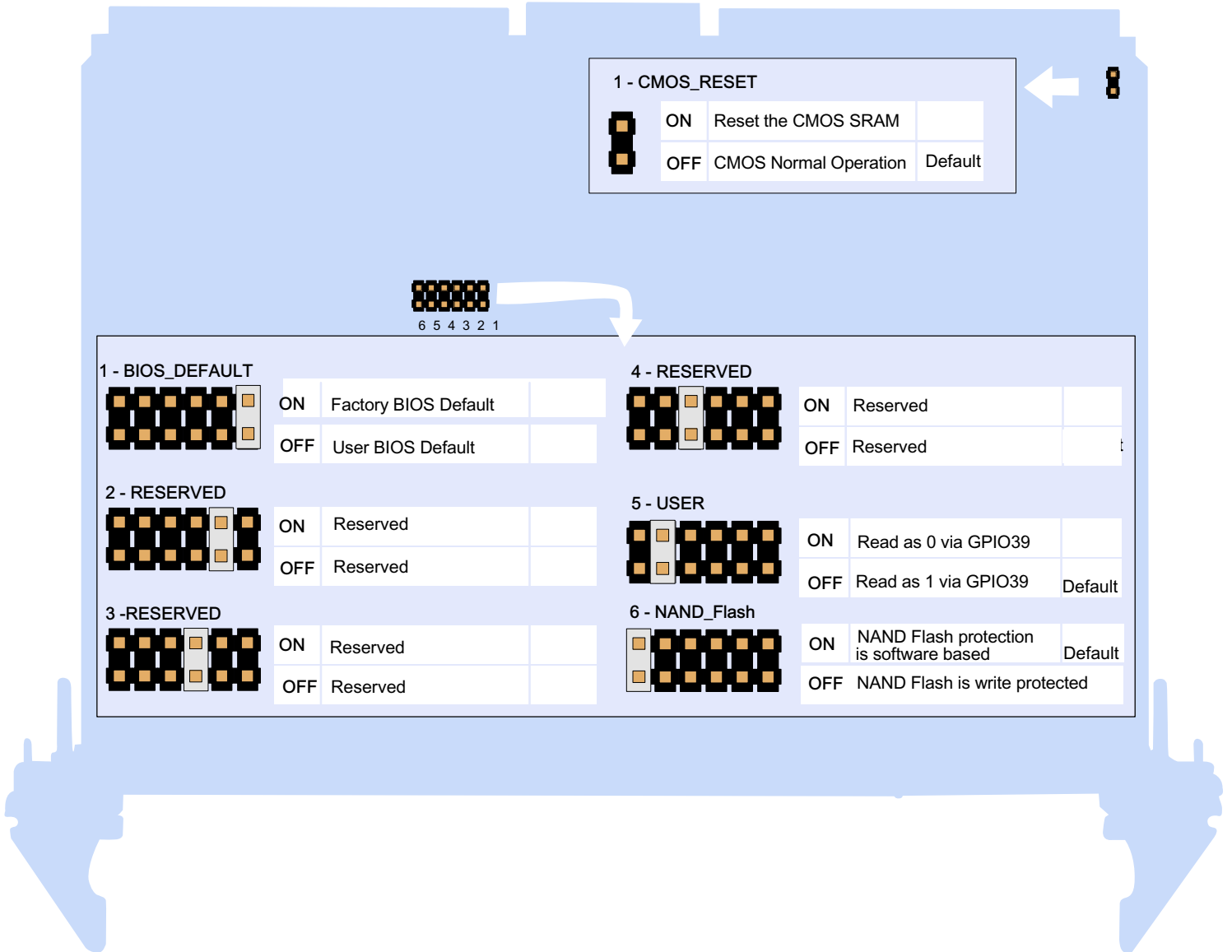


Figure 3: PENTXM2/RA & PENTXM4/RA Jumpers Locations and Default Settings

2.5.1 NAND Flash Protection

GPIO23 connects to the WP_PD# bit of the the SST55LD019 to invoke hardware write protection via a specific jumper (NAND_Flash).

- > If the local NAND_Flash jumper is installed (ON) and
 - > GPIO23 is logic 1 the NAND Flash is not write protected.
 - > GPIO23 is logic 0 the NAND Flash is write protected.
- > If the local NAND_Flash jumper is removed (OFF), the NAND Flash is write protected.

LOCATION	NAME	CONNECTS TO	SETTING	DESCRIPTION
6	NAND_Flash	6300ESB GPIO23	ON	Default configuration: NAND Flash protection is software based.
			OFF	NAND Flash is write protected.

Table 3: Jumper Description: NAND Flash Protection

» Controf of the NAND Flash Protection

The NAND Flash write protection can be managed by software with the onboard NAND_Flash jumper installed (ON) by handling the GPIO23. The GPIO23 can be set up from the BIOS firmware (release 1.00.56 and higher). Refer to section 4.2.4 “Onboard Flash Disk Write Protection” in InsydeH2O Firmware User’s Manual.

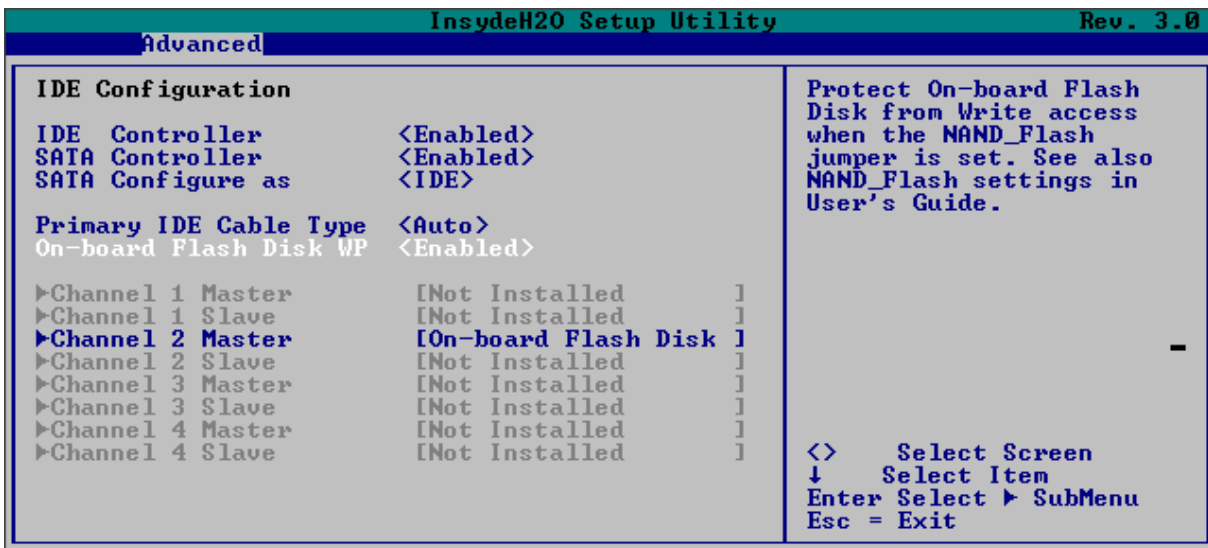


Figure 4: InsydeH2O: IDE Configuration



In the Linux RHELx BSP, a driver is provided to handle the user's GPIO: GPIO41, GPIO42 and GPIO43. The GPIO23 could be managed (output only) by adapting this driver. More detail available in:

- section 6.5.9 “User’s GPIO” in the “Release Notes RHEL4 for PENTXM2 and PENTXM4 Boards - SD.DT.E82”
- section 6.9 “User’s GPIO” in the “Release Notes RHEL5 for PENTXM2 and PENTXM4 Boards - SD.DT.F28”
- section 6.10 “User’s GPIO” in the “Release Notes RHEL5.2 for PENTXM2 and PENTXM4 Boards - SD.DT.F34”

Summary Control of NAND Flash Protection

Onboard Flash Disk WP (setup from BIOS menu)	Onboard NAND-Flash Jumper: ON	Onboard NAND-Flash Jumper:OFF
<Enabled> GPIO23=0	Onboard flash is: Write Protected	Onboard flash is: Write Protected
<Disabled> GPIO23=1	Onboard flash is: NOT Write Protected	Onboard flash is: Write Protected

Table 4: Control of the NAND Flash Protection

2.6 Mechanical Specifications

The PENTXM2/RA & PENTXM4/RA boards are built on a multi-layer double Eurocard and conforms to the dimensions specified in the ANSI/VITA VME64 1-1994. The dimensions shown below are in millimeters, with inches (in parentheses) for general guidance only.

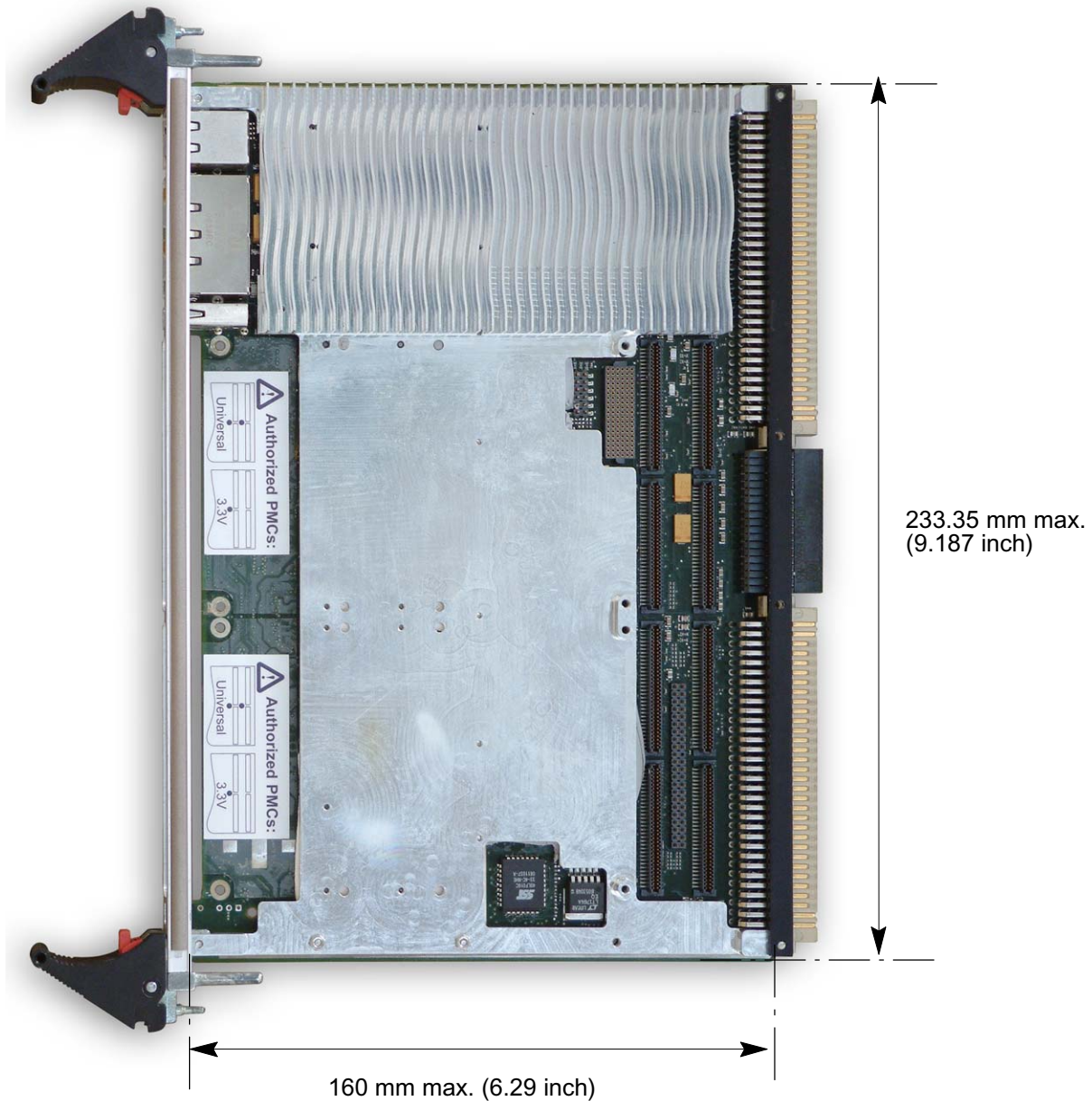


Figure 5: VME Dimensions

- Length: 233.35 mm max
- Depth: 160 mm max. (without connectors)
- Height: 1 VME slot compatible
- Weight: 670 g (approximately)

2.7 MTBF Data

Calculations are made according to the standard MIL-HDBK217F-2 for four types of environment:

- > Ground Benign (GB)
- > Air Inhabited Cargo (AIC)
- > Naval Sheltered (NS)
- > Air Rotary Wing (ARW)

	GB (Hours)		AIC (Hours)	NS (Hours)		ARW (Hours)
	25°C	40°C	40°C	25°C	40°C	55°C
PENTXM2/RA Order Code: PENTXM2-RA34S-10000	380 132	292 228	49 069	61 376	53 131	13 077
PENTXM4/RA Order Code: PENTXM4-RA34S-10000	276 979	212 257	39 202	41 713	40 247	9 622

Table 5: MTBF Data

2.8 Thermal Performance

The standard operating range for PENTXM2/RA & PENTXM4/RA is -40° to +71°C. To achieve this specification, the cooling airflow should be set according to both following graphes for PENTXM2/RA & PENTXM4/RA @1.67GHz and PENTXM2/RA & PENTXM4/RA @1.33GHz.

To modify the dual-core processing frequency, please refer to the section 6.1.1 "CPU Frequency" of the InsydeH2O Firmware User Reference Manual (SD.DT.E86).

» PENTXM2/RA - 1.67 GHz

For instance, the thermal operating point according to the PENTXM2/RA – 1.67 GHz thermal performance graph should be 3.5 m/s and 65°C for cooling airflow direction coming from PMC to CPU.

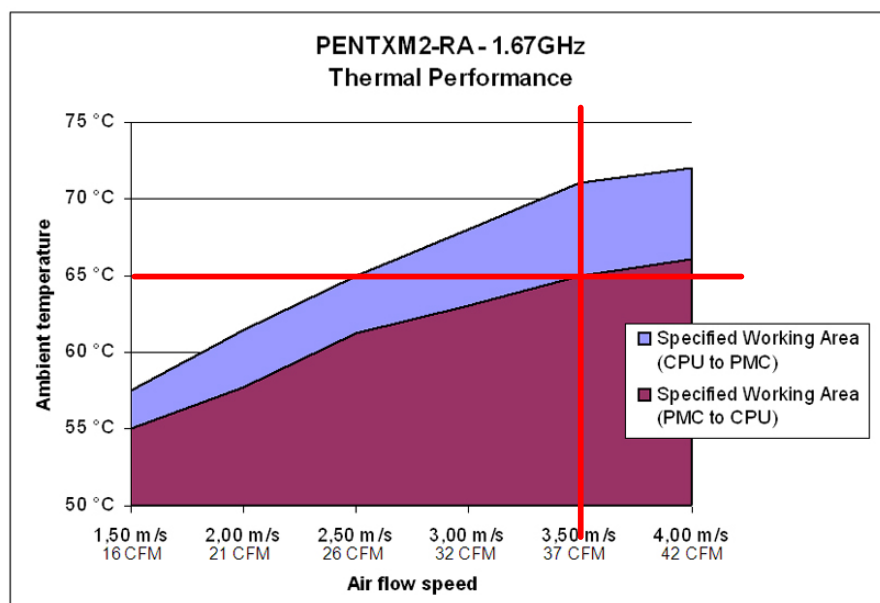


Figure 6: Thermal Performance - PENTXM2/RA @ 1.67 GHz

» PENTXM2/RA - 1.33 GHz

For instance, the thermal operating point according to the PENTXM2/RA – 1.33 GHz thermal performance graph should be 3.5 m/s and 71°C for cooling airflow direction coming from PMC to CPU.

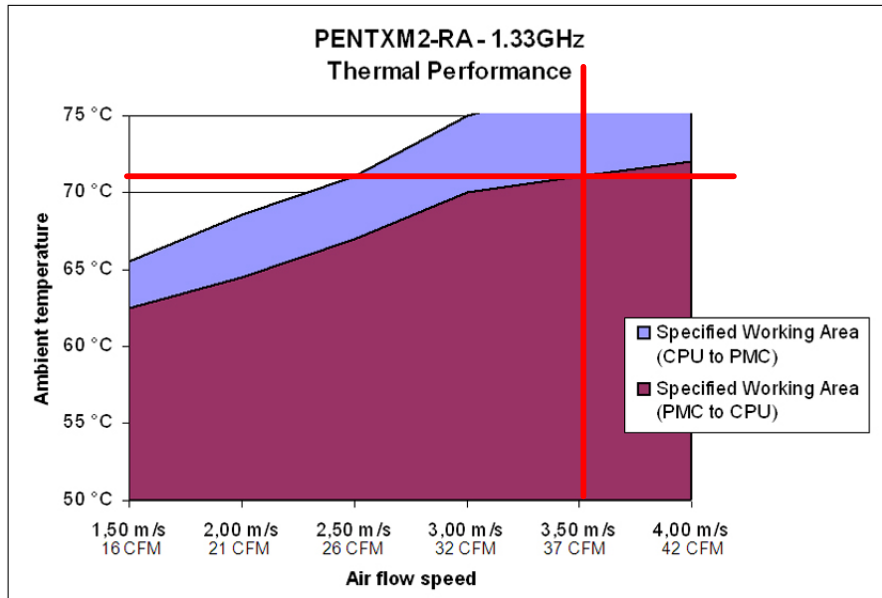


Figure 7: Thermal Performance - PENTXM2/RA @ 1.33 GHz

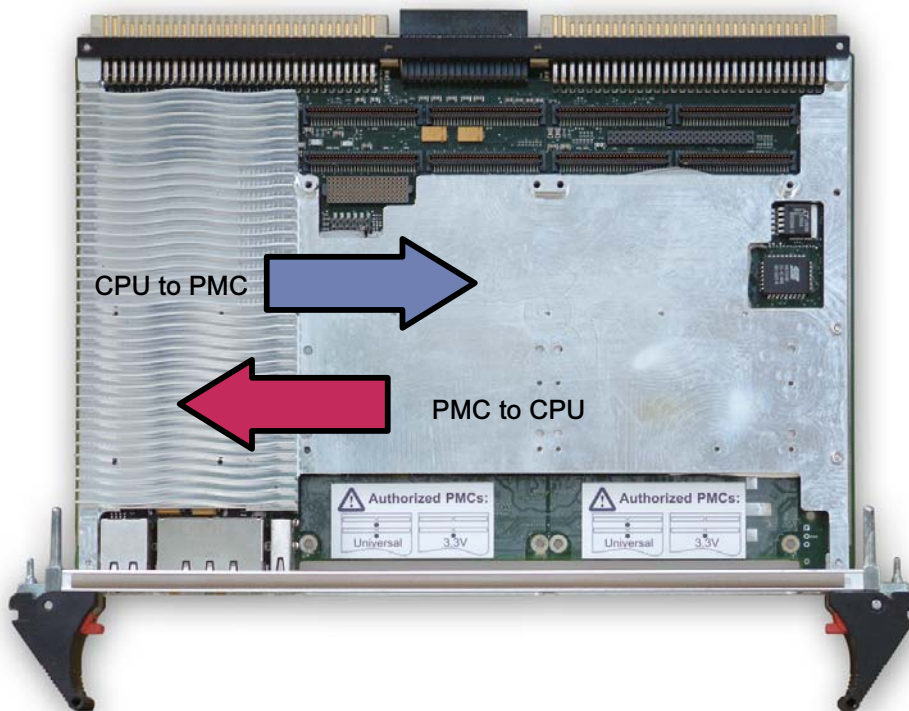


Figure 8: Air Flow Direction



The air flow direction “CPU to PMC” is more efficient.

» PENTXM4-RA-1.67GHz

For instance, the thermal operating point according to the PENTXM4/RA – 1.67 GHz thermal performance graph should be 3.2 m/s and 61°C for cooling airflow direction coming from PMC to CPU.

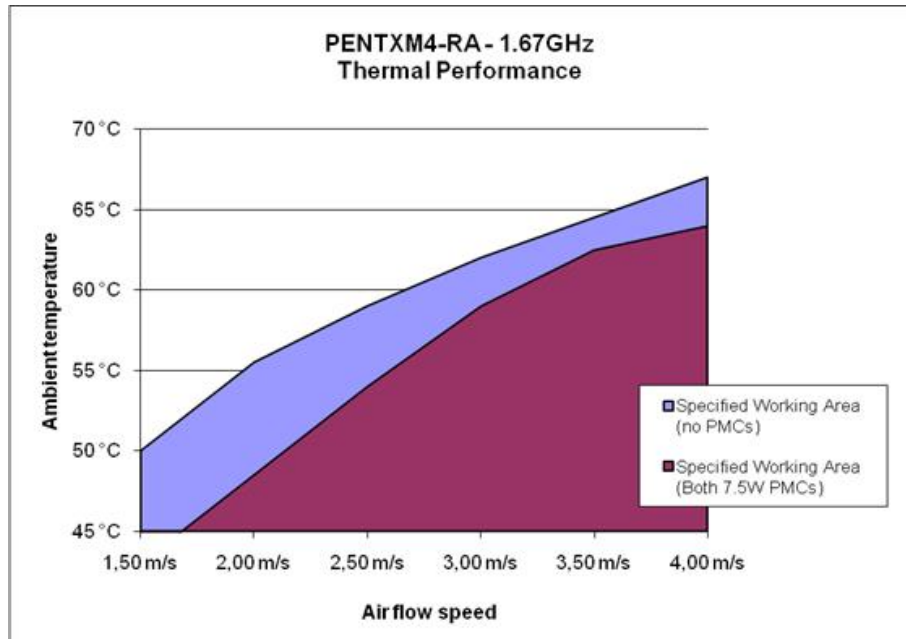


Figure 9: Thermal Performance – PENTXM4/RA @ 1.67 GHz

» PENTXM4-RA-1.33GHz

Estimated usage graph:

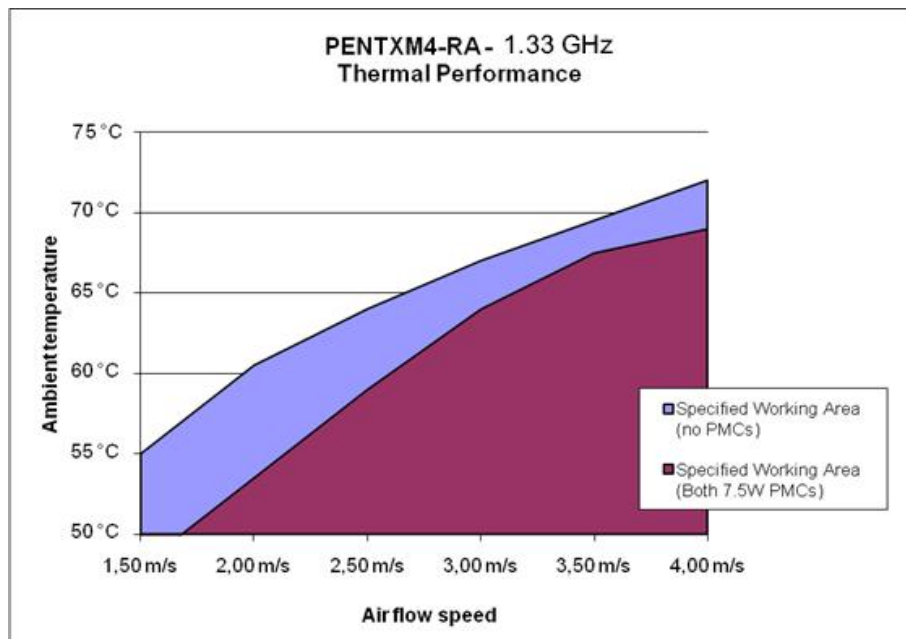


Figure 10: Thermal Performance (Estimation)– PENTXM4/RA @ 1.33 GHz

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